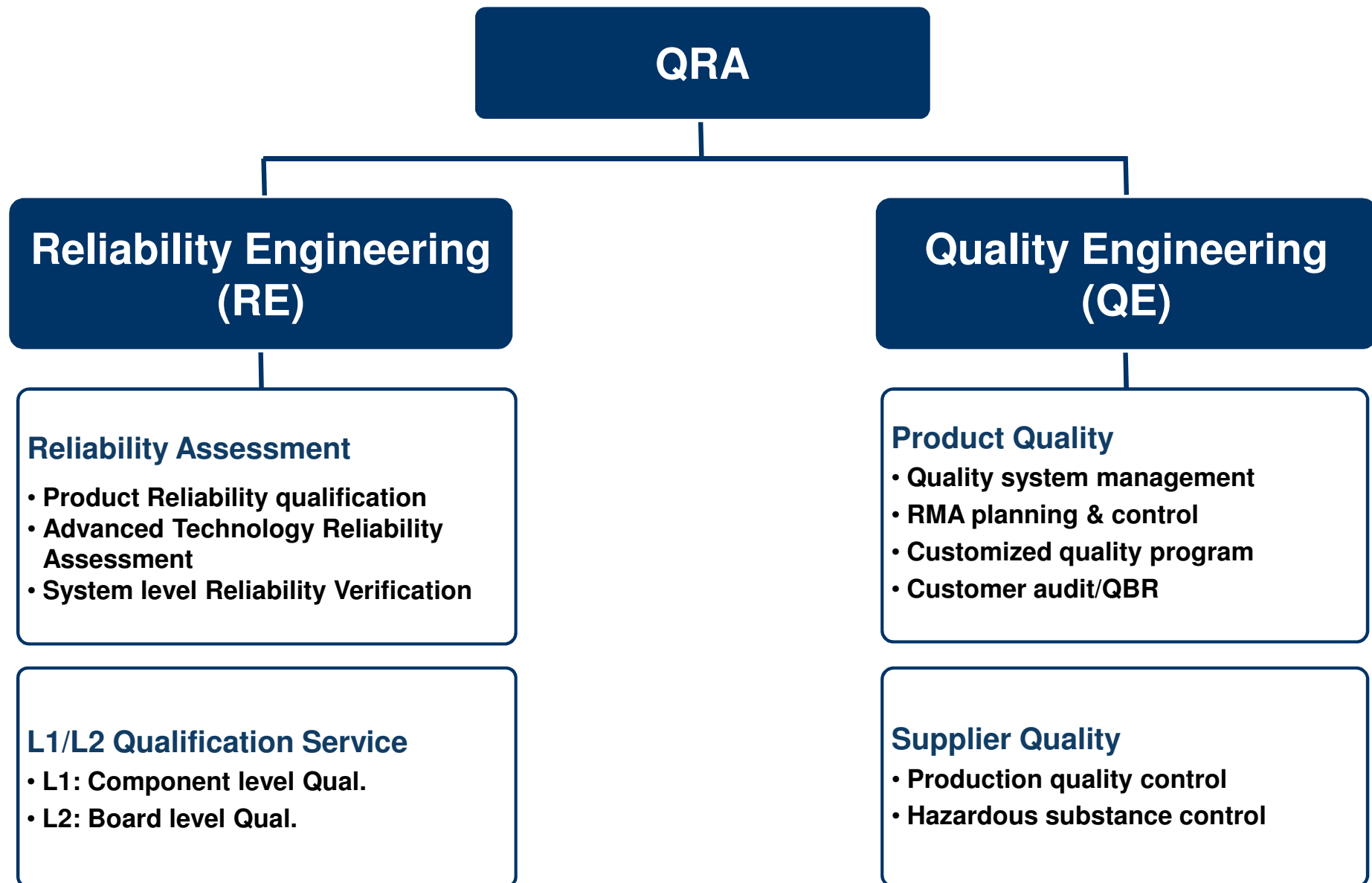




# **GUC Supplier Management/Low ppm program**

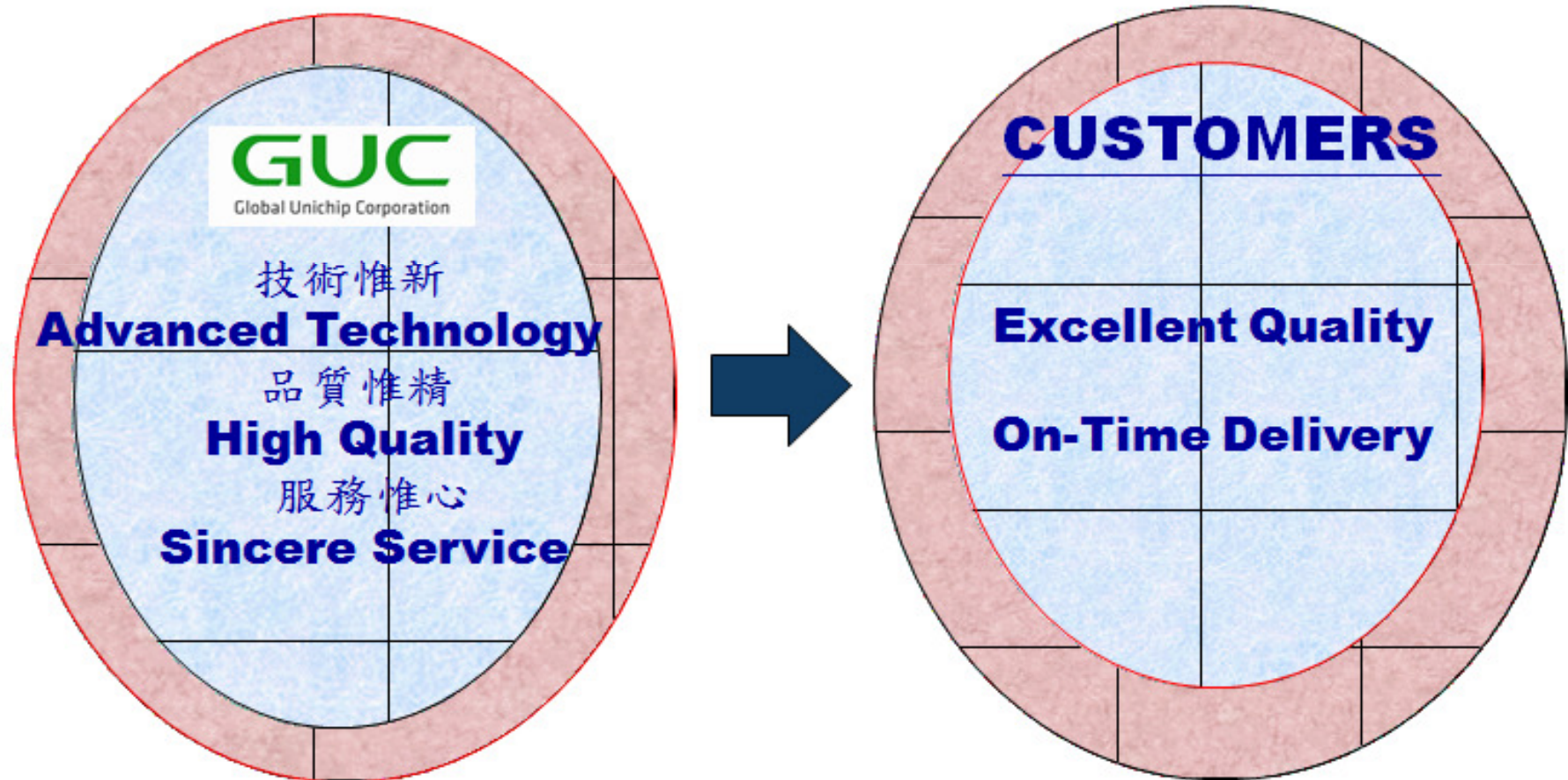
Oct 2016

# Quality & Reliability Functions



# Quality Policy

## Win - Win



# GUC Corporate Quality System

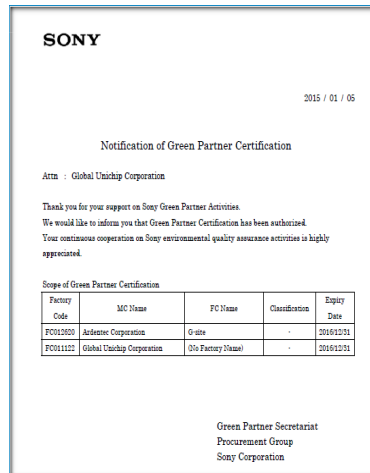
- GUC is certified by latest industry quality standards
- Qualified vendors quality comply with GUC system

ISO9001:2000 (TUV)



2001

SONY  
Green Partner



2008

IECQ/QC080000



2011

ISO9001:2008 (UL)



2012

EICC



2013

# New Supplier Quality Certificates

- GUC's suppliers should meet the capability and compliance with the required quality level at least

Certificate Vendors	ISO9001	TS16949	ISO14001	OHSAS18001	Green (SONY GP, QC080000)	IECQ17025
<b>Wafer FAB</b>	✓	✓	✓	✓	✓	✓
<b>Wafer Sort</b>	✓	✓				
<b>Assembly</b>	✓	✓	✓	✓	✓	✓
<b>Final Test</b>	✓	✓				
<b>Bench Test</b>	✓	✓				
<b>Reliability/ FA Lab</b>	✓					✓

## Notes:

ISO9001: General Quality Management Certification (Must)

ISO/TS16949: Quality Management Certification for Automotive parts

ISO14001: Environment Management Certification

OHSAS18001: Occupational health and safety Management Certification

Green/QC080000: Hazardous Substance Process Management Certification

Green/SONY GP: SONY Green Partner Certification

IECQ17025: Independent Testing Laboratory Certification

# Disciplined Manufacturing Process Control

## Pre-production

### Qualification

- JEDEC, EIAJ, AEC, MIL STD Standards
- MTTF and FIT Estimation through Reliability Model
- RoHS, Hazardous Substance Control

### Verification & Screening

- PVT (Product Verification Test) Skew
- ATE and System Correlation
- Stress Testing (Voltage/Temp.)
- Low PPM Program \*
- Automotive Program \*

## Mass Production

### Quality & Reliability Control

- Manufacturing Data Monitor
- Test Yield Management
- Maverick Control \*
- ELFR for Initial Production Lots \*
- On-going Reliability Monitor (ORM) \*

### Production & Supplier Management

- Quality Measurement and QBR
- Change Control
- Nonconforming Material Control (MRB)
- 100% Chips Visual Scanning
- On-site QC Checking \*

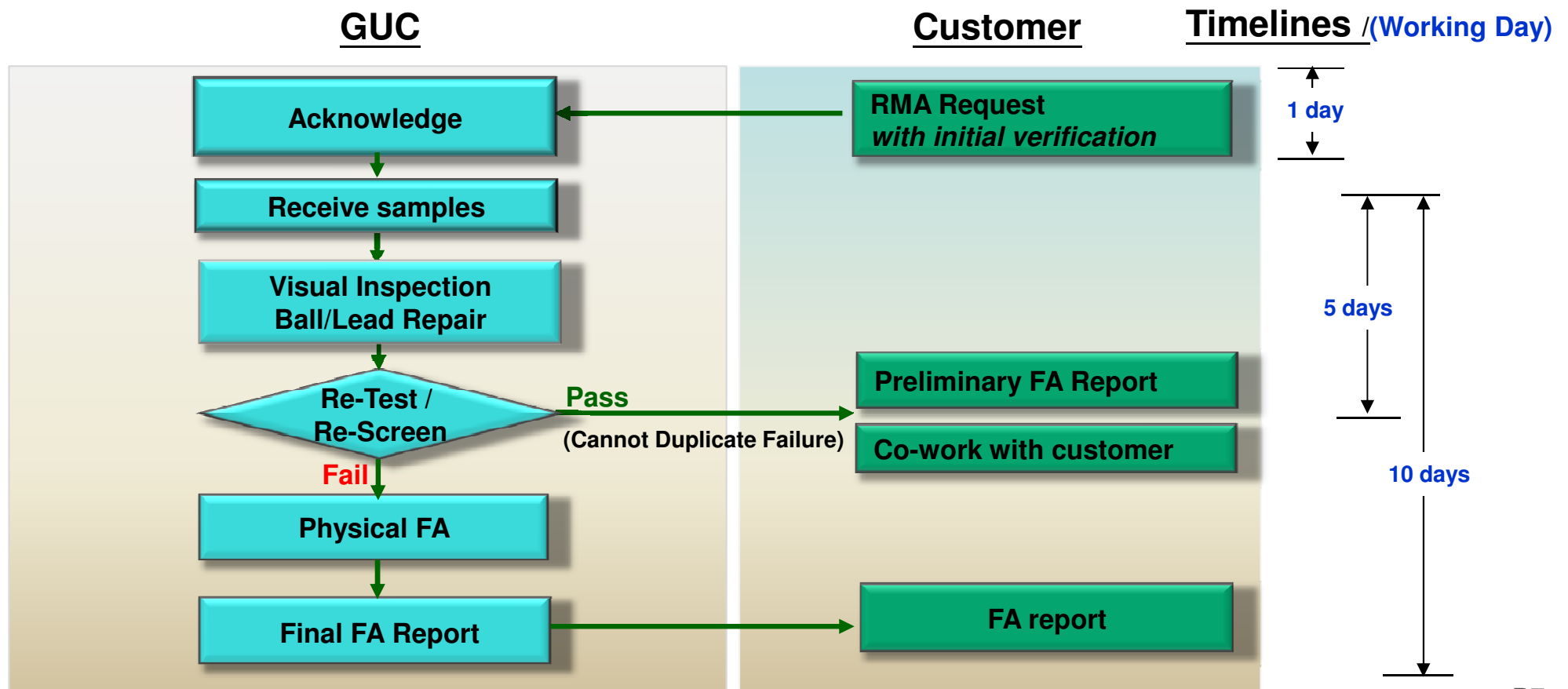
\*: Optional

P6

# RMA TAT Control

- **Component-level FA cycle time control**

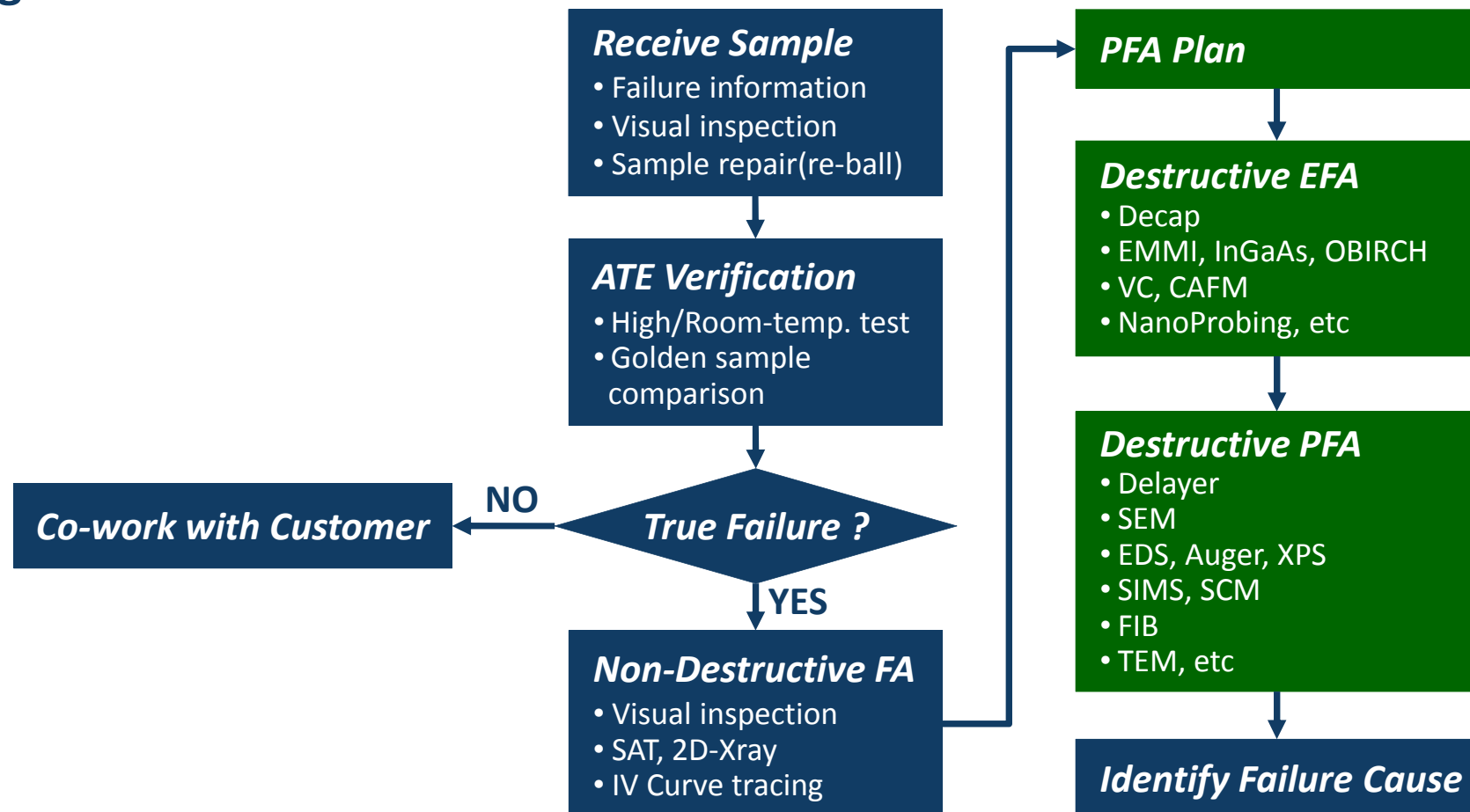
- Acknowledge: 1 working day
- Preliminary FA report: 5 working days
- Final/Status FA report: 10 working days





# Failure Analysis Support

- Support preliminary analysis, from sample repair, ATE verification and certain non-destructive FA
- GUC will propose PFA plan for Micron review and execute PFA per Micron agreement





# Failure Analysis Support

## Failure Unit in

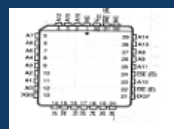
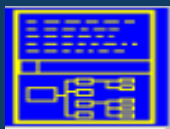
Understand  
Failure & history



Golden/ Failure  
units comparison

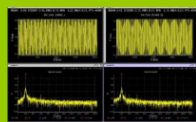


Prepare Info.  
for FA



## Non-Destructive FA

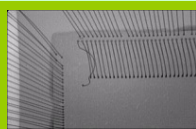
ATE



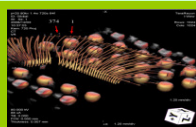
Curve trace



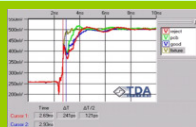
2D X-Ray



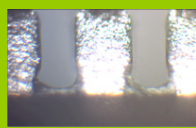
3D X-Ray



TDR



OM



SAT



## Destructive EFA

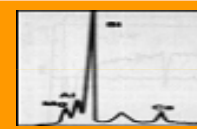
EMMI



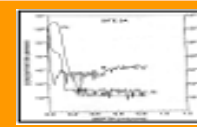
OBIRCH



EDX



SIMS



CAFM

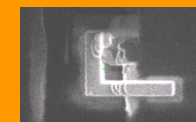


Voltage  
Contrast

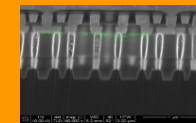


## PFA

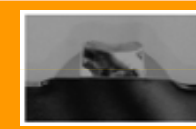
FIB



SEM



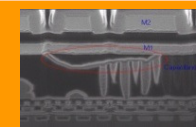
TEM



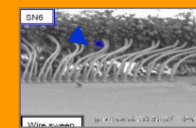
Delayer



X-Section



PA-SEM



# Change Control System

- **Engineering Change (ECN) procedure is implemented, and compliant with JEDEC/JESD46**
- **Change Category**
  - Major Change
    - A change that may affect the form, fit, function, quality, reliability, or
    - Changes that customer/GUC mutually agreed
  - Minor Change
    - A change that will not affect the form, fit, function, quality or reliability
- **Review, Notification, and Implementation**
  - QA and Product Engineer review all ECN before notification (major change) to customer or release to manufacturing site
  - Major change will be notified (thru ESN form) to customer with a minimum of **90 days** before proposed first ship date or customer/GUC agreed day

# Change Classification

## Major Change Category – compliance with JESD46

Design	Major design change
Wafer Fab	Wafer fab site
	Wafer diameter
	Diffusion dopant
	Gate oxide material
	Gate oxide thickness
	Dielectric material
	Polysilicon dopant type
	Metallization material
	Metallization thickness
	Top protective layer material
	Top protective layer thickness
	Die coating material
	Die coating thickness
	Assembly site
	Substrate or leadframe base material
	Plating material or process technique
	(BGA) Solder ball material composition
Package Assembly	Flipchip ball/bump and/or attach solder material composition
	Wire bond method
	Mold compound or underfill material
	Sealing material
	Die attach material
	Marking method
	Marking appearance (incl. Part Number marked on product)
	Test site
	Test elimination
	Burn-in change or elimination
Testing	Electrical Specification
	Change in AC specification
	Change in DC specification
	Change in case outline Loosening tolerance(s)
	Packing/Shipping/Labeling
Mechanical Specification	Change in Carrier (reel, tray) dimensions
	Drypack requirements
	Environment maximum storage temperature
	Environmental/Hazardous substance requirement

# Example Change Notice from subcon

## GUC Change Review Approval for Subcon

No. 2016-02-001

Date	2016/02/02	ESN/PCN	
User	ryan.pan	For Project	<input type="radio"/> Yes <input checked="" type="radio"/> No
Change Level	Level_A	Change Kind	Package
Reviewer	tom.kao, philip.tsai, richard.wang	Customer Inform	ryan.pan, tracy.wu, victoria.chih
Subject	ASEK_MGC material grade change from Halogenated to non-halogenated		

Job Lists of Work Flow :

### SQE

☒ Upload so-te/PCN. Attachment & Comment : SB, SE.txt CER for MGC NXA.docx CRN for MGC NXA.docx

MGC material grade change from Halogenated to non-halogenated-20160202.pdf MSDS\_GHPL830NX\_typeA\_20161127.pdf MSDS\_HL83

832NXA.830NXA\_20161007.pdf 832NXA.830NXA\_Halogen\_20161007.pdf

☒ Impact Lists. Attachment & Comment : Impact list for GUC\_0224\_Ryan.xlsx Impact device 為"N"則為非影響產品



## Engineering Specification Notice

☒ New ☐ Revise

To: ESN#: 20160401 Version#: 01  
Date: Apr 20, 2016

Dear customers,

This message is to inform you that there is an engineering specification initiate/change that requires you be informed. Please find the detail below.

If you have any concern, please feel free to contact GUC Representative...

### Subject:

Assembly subcon change the substrate from halogenated to non-halogenated.

### Product Affected:

GUC Device:

Customer Part:

### Purpose:

For environment quality enhancement, substrate supplier (MGC) will stop halogenated substrate. Non-halogenated substrate for replacement. MGC will stop production.

### Detail Description:

MGC will stop the production for halogen substrate. The substrate changed at ASE:

Process Factor	Present Value	Proposed Value
Core & P.P. material type	Core: CCL-HL 832( thickness $\leq$ 0.15mm) CCL-HL 832 HS CCL-HL 832( thickness $\geq$ 0.2mm) CCL-HL 832 EX	Core: CCL-HL 832NX(A-EX) CCL-HL 832NX(A-HS) P.P.: GHPL-830NX(A)

# Example Change Notice from subcon



GUC Confidential  
Security C

## Engineering Specification Notice

☒ New ☐ Revise

To :

ESN#: 20151002 Version#:01  
Date: Oct 19<sup>th</sup>, 2015

Dear customers,

This message is to inform you that there is an engineering specification initiate/change that requires you be informed. Please find the detail below.

If you have any concern, please feel free to contact GUC Representative.

### Subject:

FT release at KYEC

### Product Affected:

GUC Device:

Customer Part

### Purpose:

Add capacity of at KYEC site

### Detail Description:

Test program: FT1\_P03a

Please refer the detail correlation result as attached file.



U80433D  
FT@KYEC correlation

### Implementation Plan:

Once customer approved

☐ Notification only

☒ Do you agree this specification? (Y/N)

Your comment, if necessary:

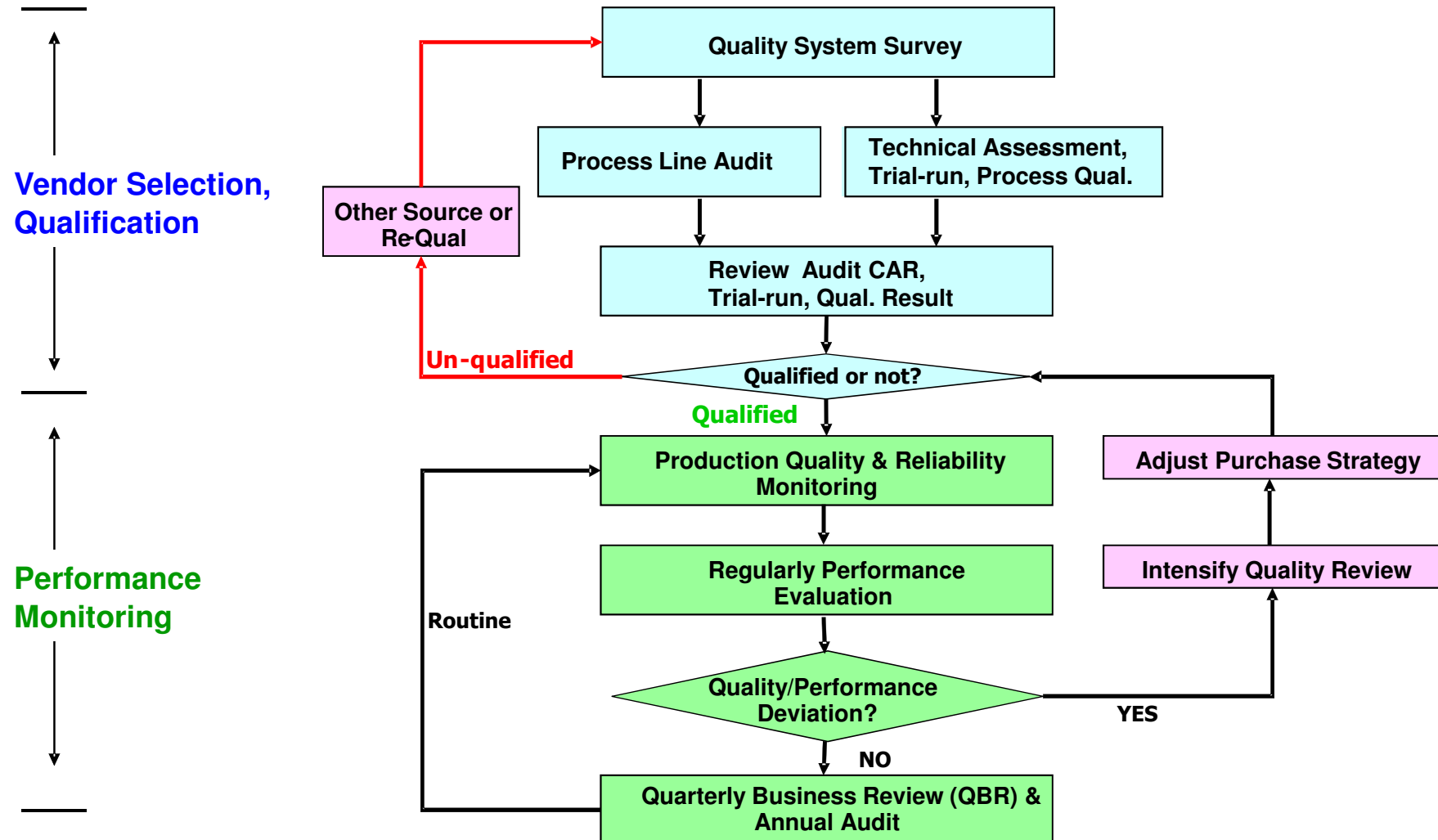
Representative:

[Signature]

Win 10/20/15

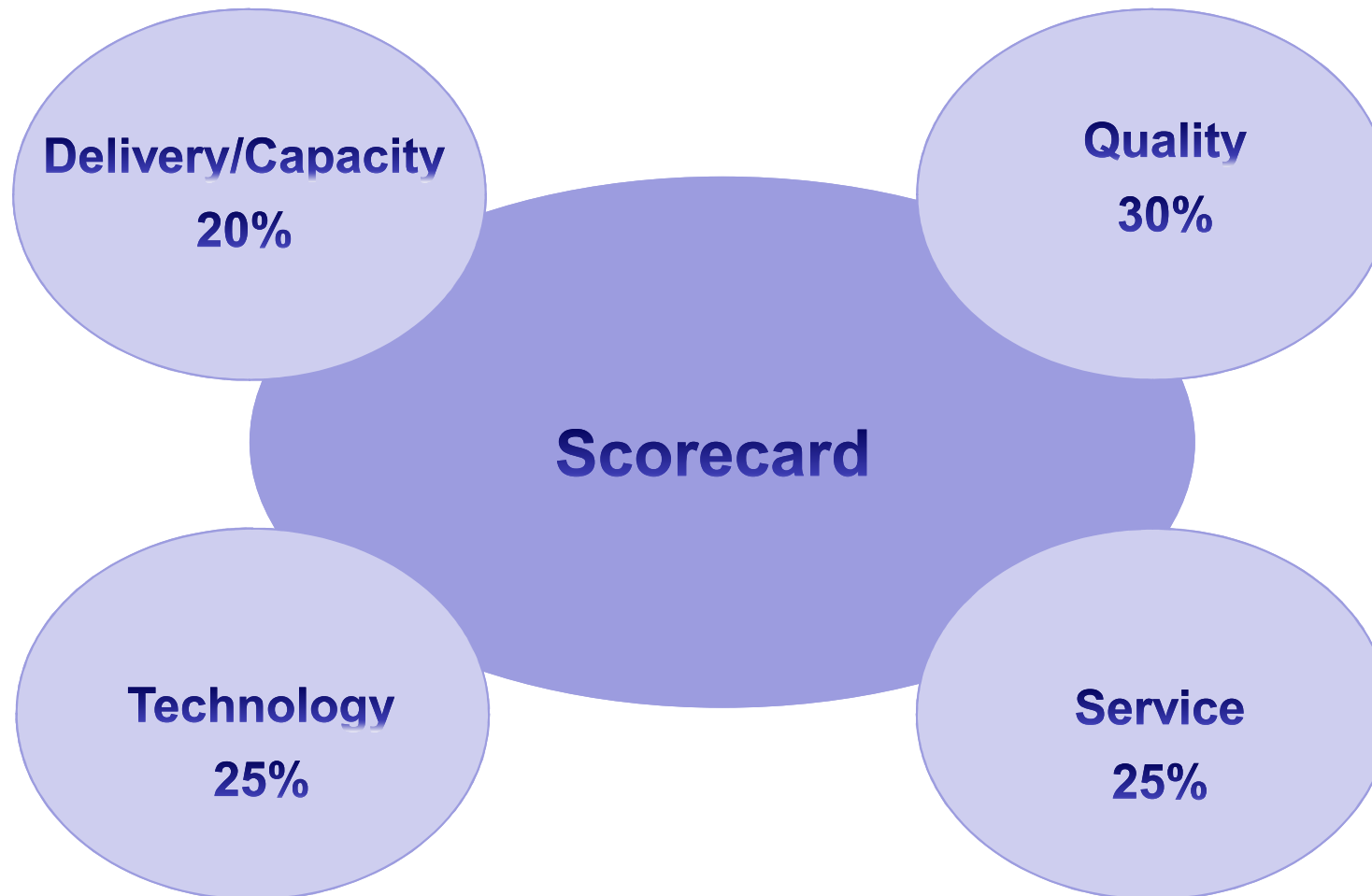
# Supplier Selection and Qualification

- Verify supplier capability to ensure the compliance with GUC Q&R level.



# Scorecard Participant Profile

- GUC's supplier will be scored in 4 directions, Delivery/Capacity, Quality, Technology and Service.
- The QBR is based on *Supplier Performance Review Procedure (10-06-09-000)*.





# Ranking

- **GUC QBR Scorecard Guideline**

--- GUC will request Improvement plan once score is lower than

--- Disqualified if continuous 2 times in grade E without improvement

Classification	Score	Level	Description
A	Above 90.0	Excellent	To Preserve a status / Condition
B	80.0-89.9	Satisfactory	Minimum improvement expected
C	70.0-79.9	Fair	Improvement required
D	60.0-69.9	Below average	Maximum improvement required
E	Under 60.0	Poor	Probation with Maximum improvement

# Quality & Delivery/Capability (Fab)

-- Quality Owner: Q&R

-- Delivery/Capability Owner: PP

	TSMC			Q2 2016	
Category	Evaluating items	Sub-score	Criteria	Score	Comment
Q U A L I T Y	[End-Customer] Field Nonconforming Case	15	15 No compliant from GUC customer		
			10 One compliant from GUC customer per quarter		
			5 One compliant from GUC customer per month		
			0 More than one compliant from GUC customer per month		
	[End-Customer] RMA / FA TAT GUC goal: Preliminary reply(3D): 3 days; formal CAR(8D): 7 days	15	15 100% meet the GUC's goal		
			10 100% meet the committed TAT, but don't meet GUC's goal		
			5 Cannot 100% meet the committed TAT		
			0 Cannot provide the committed TAT		
	[End-Customer] FA success rate	10	10 FA success rate >= 80%		
			5 FA success rate >= 50%		
			0 FA success rate < 50%		
	[End-Customer] Support for Product/Production Information Collection	15	15 Provided 100% timely and correctly		
			10 Delay, or incorrect but provide update quickly		
			5 Delay, or incorrect but provide update after several reminders		
			0 Delay and impact GUC's report to end customer		
	[Production Control] Process Nonconforming Case	15	15 No nonconformance or reject per month (AVG)		
			10 Two nonconformance or reject per month (AVG)		
			5 Four nonconformance or reject per month (AVG)		
			0 More than Four nonconformance or reject per month (AVG)		
	[Production Control] FAB event responsiveness	15	15 Timely inform the quality event in 24 hours		
			10 Inform the quality event in 48 hours		
			5 Inform the quality event longer than 48 hours		
			0 No notification		
	[Production Control] Yield improvement	15	15 All products meet tsmc's model yield		
			10 80% products meet tsmc's model yield.		
			5 50% products meet tsmc's model yield.		
0 Below 50% products meet tsmc's model yield.					
	Total:	100	Total Score:	0	

	TSMC			Q2 Y2016	
Category	Evaluating items	Sub-score	Criteria	Score	Comment
/ D E L I V E R Y  / C A P A B I L I T Y	CLIP/CVP (Confirmed Line Item Performance) (Confirmed Volume Performance)	20	20 97.5 ~ 100%		
			15 90 ~ 97.5%		
			10 85% ~ 90%		
			5 80% ~ 85%		
			0 <80%		
	Production Cycle time Hit Rate	20	20 90 ~ 100% compared to target cycle time		
			15 80 ~ 90% compared target cycle time		
			10 70 ~ 80% compared target cycle time		
			5 60 ~ 70% compared target cycle time		
			0 <60% compared target cycle time		
	Capacity/Allocation	20	20 95% ~ 100% meet GUC expectation		
			15 90% ~ 95% meet GUC expectation		
			10 85% ~ 90% meet GUC expectation		
			5 80 ~ 85% meet GUC expectation		
			0 <80% meet GUC expectation		
	Rescheduling Flexibility	20	20 Fully fulfill all pull in & push out request		
			10 Partial fulfill all pull in & push out request		
			0 Reject all pull in & push out request		
	Logistics Support 1. WIP data accuracy 2. Holiday /weekend support 3. Shipping arrangement 4. Response time	20	20 Fully support and meet all GUC expectation		
			10 > 50% meet GUC expectation		
			0 Inflexible and <50% meet GUC expectation		
Total:	100	Total Score:	0		

(10-06-09-001).

# Technology & Service (Fab)

-- Technology Owner: PE/DS

-- Service Owner: Purchaser and all

	TSMC			Q2 2016	Comment
	Evaluating items	Sub-score	Criteria	Score	
T E C H N O L O G Y	Technology Roadmap	15	15 Proactively provide Technology Roadmap & knowledge		
			10 Provide Technology Roadmap & knowledge upon request		
			5 Provide limited Technology Roadmap & knowledge		
			0 Can not provide Technology Roadmap & knowledge		
	Design support response time	15	15 Reply proposal within 48 hours		
			10 Reply proposal within 96 hours		
			5 Reply proposal after 96 hours		
			0 cannot reply		
	Design documentation	15	15 Provide complete/corrective documents		
			10 Provide partial documents		
			0 Cannot provide document		
	Quality	25	25 IP/Design quality meet application requirement		
			15 One project suffered IP/design quality issue		
			5 Two projects suffered IP/Design quality issue		
			0 More than two projects suffered IP/Design quality issue		
	Testing solution	15	15 Provide production solution		
			10 Provide partial production solution		
			5 Provide engineering solution, but no production solution.		
			0 Cannot provide any solution		
	FA cycle time & success rate	15	15 Reply plan within 48 hours, and submit report on committed schedule		
			10 Reply plan after 48 hours, submit report on committed schedule		
			5 Reply plan within 48 hours, does not submit report on committed schedule		
			0 Cannot provide plan and report		
	Total:	100	Total Score:	0	

	TSMC			Q2 2016	Comment
	Evaluating items	Sub-score	Criteria	Score	
S E R V I C E	Response & follow up Fulfillment	25	25 100% fulfillment		
			15 Satisfactory		
			0 Poor support		
	Meeting efficiency & accuracy	25	25 100% fulfillment		
			15 Satisfactory		
			0 Poor support		
	Proactive service	25	25 100% fulfillment		
			15 Satisfactory		
			0 Poor support		
	Resource support (Manpower, design resource, engineering, QA support)	25	25 100% fulfillment		
			15 Satisfactory		
			0 Poor support		
	Total:	100	Total Score:	0	

(10-06-09-001).

# Quality & Delivery/Capability (ASSY)

-- Quality Owner: Q&R

-- Delivery/Capability Owner: PP

ASE		Rated by: QRA			
Evaluation Items	Sub-score	Criteria			Score
RMA/CCN	30	Case	10	-10 per case	
		Impact Rate (IR)	10	IR < 10000 ppm	
			5	10000 ≤ IR < 50000 ppm	
			0	IR ≥ 50000 ppm, or line down	
		3D(4D)/8D	5	-5 per delay times	
LQI/RN (Low yield Flag: 99.00%)	20	Final 8D/AR update	5	-5 per delay times	
		Case	5	-5 per case	
		Impact q'ty	5	<50K	
			3	50~100K	
			0	>100K, or Line down	
Yield performance	20	3D(4D)/8D	5	-5 per delay times	
		Average assembly yield (Y) (Yield Goal: G)	20	Y-G ≥ 0.35%	
			10	0% ≤ Y-G < 0.35%	
			5	-0.50% ≤ Y-G < 0%	
			0	Y-G < -0.50%	
ECN implementation	20	Implementation & response	20	100% & proactive response w/evidence	
			10	100% implementation	
			0	no 100% implementation or delay	
			0	no 100% implementation or delay	
RoHS survey service	10	Case	10	100% meet and urgent case support	
			5	100% on time	
			0	Any case delay, poor report quality or not support urgent case	
			0	Any case delay, poor report quality or not support urgent case	

ASE		Rated by: PP			
Evaluation	Sub-total	Criterion			Score
<b>CLIP &amp; CVP</b> Commit Line Item Performance Commit Volume Performance	20	20	98 ~ 100%		
		15	90 ~ 97%		
		10	85% ~ 89%		
		5	80% ~ 84%		
		0	<80%		
<b>Cycle time support</b> 1. Including Production/Engineering modes 2. Comparison among competitors 3. Comparison to supplier standard cycle time	20	20	Best performance compared to all competitors		
		15	Similar to competitors most of the times/ Meet supplier standard cycle time		
		5	Worse than competitors most of the times		
		0	Lead time not predictable, not a dependable supplier		
<b>Capacity booking /Allocation</b>	20	20	95% ~ 100%		
		15	90% ~ 95%		
		10	85% ~ 90%		
		5	80 ~ 85%		
		0	<80%		
<b>Pull-in or Push out rescheduling flexibility</b>	20	20	Fully support and meet all GUC expectation		
		15	Excellent support and >90% meet GUC expectation		
		5	support and >50% meet GUC expectation		
		0	Inflexible and <50% meet GUC expectation		
<b>Logistics Support</b> 1. WIP data accuracy 2. Holiday/weekend support 3. Product information 4. Response/feedback time (within 2 days)	20	20	Fully support and meet all GUC expectation		
		15	Excellent support and >75% meet GUC expectation		
		10	Good support and >50% meet GUC expectation		
		0	Inflexible and <50% meet GUC expectation		

(10-06-09-001).

# Technology & Service (ASSY)

-- Technology Owner: PE

-- Service Owner: Purchaser and all

ASE		Rated by: PA	
Evaluation	Sub-total	Criterion	Score
<b>New Technology support</b> -Roadmap update -Knowledge sharing -Tech. inquiry response	10	10 Proactively provide Technology Roadmap & knowledge	
		7 Provide Technology Roadmap & knowledge upon request	
		3 Provide limited Technology Roadmap & knowledge	
		0 Can't provide Technology Roadmap & knowledge	
<b>1. New product development support - SB base</b> -Substrate 1st design process time can't meet commit ( 7~14 days, case by case) -Substrate modify process time can't meet commit (3~5 days, case by case) -Substrate design violate constraint -Modify frequency -Design quality	45	Meet basic support 34 -2 per case delay +2 per case pull in -3 per case if modification frequency over 4 times +3 per case if modification frequency under 2 times -5 per case if design fail +3~5high volume(compared with competitors) and without any failure	
<b>2. New product development support - LF base</b> -BD delivery (>3 days delivery fail ) -Design quality			
<b>Engineering support and troubleshooting</b> -Electrical simulation cycle time(target 14 days) -Thermal simulation cycle time(target 10 days) -Data accuracy -Pilot ENG issue solve -Engineering troubleshooting -Special DOE support	20	Meet basic support 15 -2 per case delay +2 per case pull in -1 per case if wrong data +1 per special DOE support +1 per case for ENG issue solved or troubleshooting proactively -2 per case for ENG poor support or troubleshooting fail	
<b>Pilot Assembly Yield improve &amp; Enhance</b> -Pilot lot /ENG lot assy yield > 98% -improve plan and response	10	Meet target yield score 7 +1 per case meets GUC's goal & with improve activities -1 per case if assy yield < 98% -2 per case if low yield without improve plan	
<b>Pilot O/S ratio/ FA &amp; improvement</b> -Pilot lot O/S <1% (exclude non-cp wafer) -FA: 3days preliminary report -FA: 7days final report -improve plan and response	15	Meet target & basic support 12 +1 per case if its yield meets GUC's goal & keep improve activities -1 per case if O/S >1% -2 per case if O/S > 1% and no improve plan -1 per case if FA delay	

ASE		Rated by: QRA	
Evaluation Items	Sub-score	Criteria	Score
FA/Reliability support	20	Case	20 100% meet and urgent case support
			15 100% meet
			10 90% meet
			0 < 90% meet
Action request	40	Case	40 100% meet and urgent case support
			30 100% on time
			20 one case delay or poor report quality
			0 Two more cases delay or not support urgent case
Continuous improvement	30	Case	30 Proactive plan
			20 Act as required in need
			10 Not implemented
			0 Not implemented as required
Meeting efficiency	10	Case	10 100% on time & AR follow-up
			5 one case delay or poor report quality
			0 Two more cases delay

(10-06-09-001).

# Service (ASSY)

-- Service Owner: Purchaser and all

ASE		Rated by: PP		
Evaluation	Sub-total	Criterion		Score
Response & follow up Fulfillment	25	25	Proactive support with 100% fulfillment	
		20	Very satisfactory & minimum improvement required	
		15	Satisfactory & improvement required	
		10	Below average & maximum improvement required	
		0	Poor support & maximum improvement required immediately	
Meeting efficiency & accuracy	25	25	Proactive support with 100% fulfillment	
		20	Very satisfactory & minimum improvement required	
		15	Satisfactory & improvement required	
		10	Below average & maximum improvement required	
		0	Poor support & maximum improvement required immediately	
Proactive service	25	25	Proactive support with 100% fulfillment	
		20	Very satisfactory & minimum improvement required	
		15	Satisfactory & improvement required	
		10	Below average & maximum improvement required	
		0	Poor support & maximum improvement required immediately	
Resource & capacity support	25	25	Proactive support with 100% fulfillment	
		20	Very satisfactory & minimum improvement required	
		15	Satisfactory & improvement required	
		10	Below average & maximum improvement required	
		0	Poor support & maximum improvement required immediately	

ASE		Rated by: PA		
Evaluation	Sub-total	Criterion		Score
Resource support (Manpower, design resource, engineering support)	40	40	Proactive support with 100% fulfillment	
		35	Very satisfactory & minimum improvement required	
		30	Satisfactory & improvement required	
		20	Below average & maximum improvement required	
		0	Poor support & maximum improvement required immediately	
Communication efficiency	30	30	Proactive support with 100% fulfillment	
		20	Satisfactory & improvement required	
		10	Below average & maximum improvement required	
		0	Poor support & maximum improvement required immediately	
Action follow up and response quality	30	30	Proactive support with 100% fulfillment	
		20	Satisfactory & improvement required	
		10	Below average & maximum improvement required	
		0	Poor support & maximum improvement required immediately	

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# Quality & Delivery/Capability (Test)

-- Quality Owner: Q&R

-- Delivery/Capability Owner: PP

ASE		Rated by: QRA		
Evaluating items	Sub-score	Criteria		Score
<b>End-Customer Service Nonconforming Case</b> (Score deduction doubled for serious events)	30	30	No complaint from GUC customer	
		20	1 complaint(not repeating failure) from GUC customer	
		10	1 complaint(repeating failure) from GUC customer	
		0	>=2 complaints from GUC customer	
<b>End-Customer Service</b> 1. Nonconforming case request handling & response GUC goal: Preliminary reply(3D): 3 days Formal CAR(8D): 7 days 2. Customer special request handling & response GUC goal: According to customer request	15	15	Meet the GUC's goal	
		10	Can't meet committed date but notify GUC with agreement for rescheduling	
		0	Can't meet the committed day & didn't notify GUC to reschedule or no effective actions	
<b>IQC failure rate</b> (Score deduction double if delivery impacted or same defect repeatedly)	15	15	No reject by GUC or GUC's suppliers	
		10	One reject case by GUC or GUC's suppliers in the month	
		5	Two reject cases by GUC or GUC's suppliers in the month	
		0	more than two reject cases by GUC or GUC's suppliers in the month	
<b>Average Loss Rate</b> (Score deduction doubled if 1. Loss rate > 300ppm without improve action 2. Single lot loss rate > 300ppm without improve action)	10	10	Loss rate < 50 ppm	
		5	Loss rate < 100 ppm, > 50 ppm	
		0	Loss rate < 300 ppm, > 100 ppm	
<b>ECN supporting</b>	5	5	Timely informed & approved before change	
		0	One case inform delayed but still get approval before change	
<b>Others</b>	25	0-25	Proactively work with GUC on CIP project	
			Proactively work with GUC on 8D follow up and/or close	
			Proactively at IQC gating and cath quality issues from oither subcons	
			Proactively initiate and report on subcon CIP project for GUC/customer baseline improvement	

ASE		Rated by: PP		
Evaluation	Sub-total	Criterion		Score
<b>CLIP &amp; CVP</b> Commit Line Item Performance Commit Volume Performance	20	20	98 ~ 100%	
		15	90 ~ 97%	
		10	85% ~ 89%	
		5	80% ~ 84%	
		0	<80%	
<b>Cycle time support</b> 1. Including Production/Engineering modes 2. Comparison among competitors 3. Comparison to supplier standard cycle time	20	20	Best performance compared to all competitors	
		15	Similar to competitors most of the times/ Meet supplier standard cycle time	
		5	Worse than competitors most of the times	
		0	Lead time not predictable, not a dependable supplier	
<b>Capacity booking /Allocation</b>	20	20	95% ~ 100%	
		15	90% ~ 95%	
		10	85% ~ 90%	
		5	80 ~ 85%	
		0	<80%	
<b>Pull-in or Push out rescheduling flexibility</b>	20	20	Fully support and meet all GUC expectation	
		15	Excellent support and >90% meet GUC expectation	
		5	support and >50% meet GUC expectation	
		0	Inflexible and <50% meet GUC expectation	
<b>Logistics Support</b> 1. WIP data accuracy 2. Holiday/weekend support 3. Product information 4. Response/feedback time (within 2 days)	20	20	Fully support and meet all GUC expectation	
		15	Excellent support and >75% meet GUC expectation	
		10	Good support and >50% meet GUC expectation	
		0	Inflexible and <50% meet GUC expectation	

(10-06-09-001).



# Technology & Service (Test)

-- Technology Owner: TE

-- Service Owner: Purchaser and all

ASE		Rated by: TED	
Evaluation	sub-total	Criterion	Score
CP Re-test Yield Gain	20	Meet the GUC's goal : 17 1. Each reduce 1% (+3) 2. Each increase 1% (-3)	
FT Re-test Yield Gain	25	Meet the GUC's goal : 22 1. Each reduce 1% (+3) 2. Each increase 1% (-3)	
Hold Lot Cycle Time	25	Meet the GUC's goal : 22 1. Each reduce 1 hour (+3) 2. Each increase 1 hour (-3)	
FA Performance -Troubleshooting	15	Meet basic requirement: 12 1. Each feedback delay (-3) 2. Each weakness (-3) 3. Each strength (+3) Weakness : No report by committed schedule or FA unsuccessful Strength : Submit report by committed schedule and FA successful	
Capability 1. Testing 2. Supporting 3. Hardware improvement 4. Software improvement	15	Meet basic requirement: 11 1. Each feedback delay (-2) 2. Each weakness (-2) 3. Each strength (+2) Weakness : Poor service or fail GUC's task Strength : Proactive and provide effective solution to GUC	

ASE		Rated by: QRA		
Evaluation Items	Sub-score	Criteria		Score
FA/Reliability support	20	Case	20	100% meet and urgent case support
			15	100% meet
			10	90% meet
			0	< 90% meet
Action request	40	Case	40	100% meet and urgent case support
			30	100% on time
			20	one case delay or poor report quality
			0	Two more cases delay or not support urgent case
Continuous improvement	30	Case	30	Proactive plan
			20	Act as required in need
			10	Not implemented
			0	Not implemented as required
Meeting efficiency	10	Case	10	100% on time & AR follow-up
			5	one case delay or poor report quality
			0	Two more cases delay

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# Service (Test)

-- Service Owner: Purchaser and all

ASE		Rated by: PP		
Evaluation	Sub-total		Criterion	Score
Response & follow up Fulfillment	25	25	Proactive support with 100% fulfillment	
		20	Very satisfactory & minimum improvement required	
		15	Satisfactory & improvement required	
		10	Below average & maximum improvement required	
		0	Poor support & maximum improvement required immediately	
Meeting efficiency & accuracy	25	25	Proactive support with 100% fulfillment	
		20	Very satisfactory & minimum improvement required	
		15	Satisfactory & improvement required	
		10	Below average & maximum improvement required	
		0	Poor support & maximum improvement required immediately	
Proactive service	25	25	Proactive support with 100% fulfillment	
		20	Very satisfactory & minimum improvement required	
		15	Satisfactory & improvement required	
		10	Below average & maximum improvement required	
		0	Poor support & maximum improvement required immediately	
Resource & capacity support	25	25	Proactive support with 100% fulfillment	
		20	Very satisfactory & minimum improvement required	
		15	Satisfactory & improvement required	
		10	Below average & maximum improvement required	
		0	Poor support & maximum improvement required immediately	

ASE		Rated by: TED		
Evaluation	Sub-total		Criterion	Score
Service Efficiency 1. Engineering data 2. Test result 3. Special request	100		Meet Basic support 75 1. Each feedback delay (-5) 2. Each weakness (-5) 3. Each strength (+5) Weakness : No data reply within 96 hrs after request Strength : Provide useful data proactively and real time	

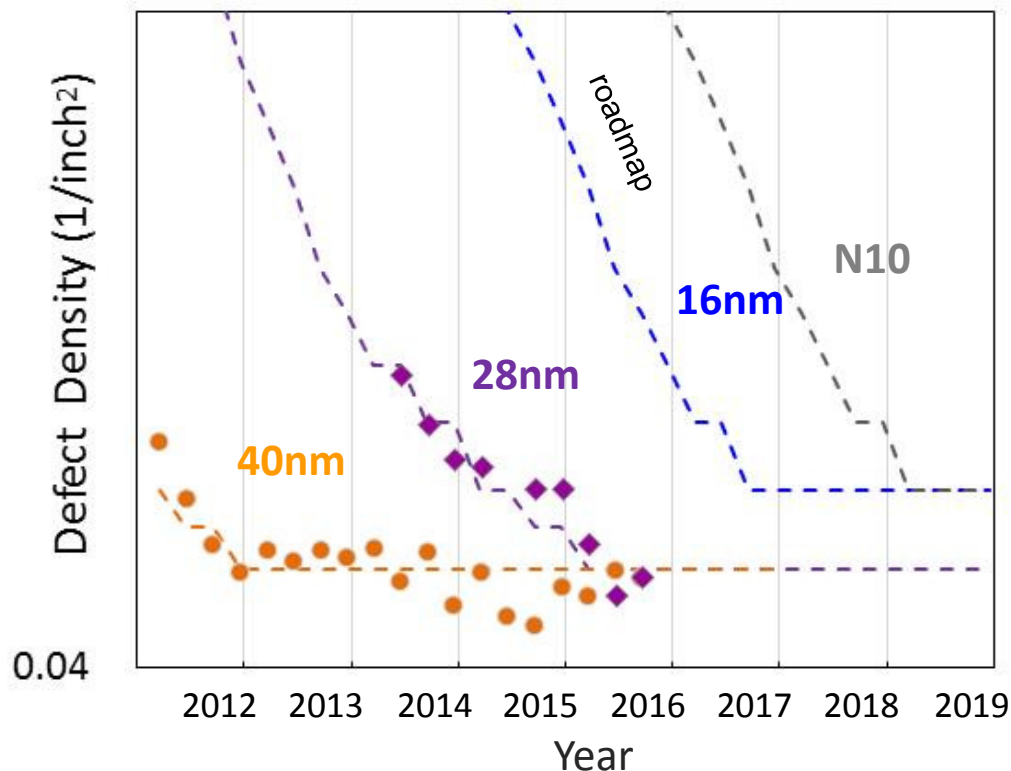
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# **Automotive/Low PPM program introduction**

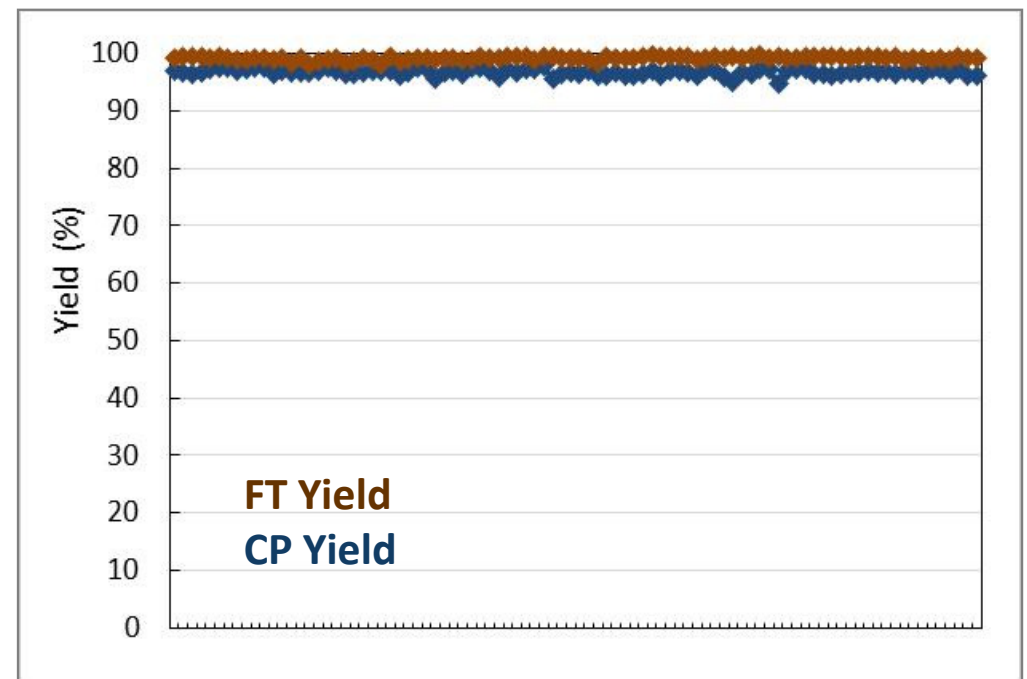
# Better Yield than Manufacturer Roadmap

- Good relationship and working with all manufacturers for BKM and improvement.
- Experienced PE engineers with FAB expertise to work closely with tsmc to achieve better yield performance than manufacturing roadmap.

*Actual D0 vs. Roadmap*



*65nm Automotive Product CP&FT Yield*



# Realize Your Chips for Automotive Requirements

- Incorporating GUC automotive solutions and TSMC automotive service package for your quality/reliability targets.

**Development Phase**

- Package Solution (Simulation, Co-Design)
- Testing for ppm target, AEC Q100s and risk level
- Qual for AEC Q100s
- Audit/Part Approval process for TS16949, VDA6.x

**Production Phase**

- TSMC Automotive Service
- GUC ZERO Defect Program
- Safe Launch for New Product Introduction

**Finish\_Good ASIC**

**After-Service Phase**

- Quick FA/RMA and CAR reporting

# GUC Automotive Projects Update

- Flexible service model to support automotive part production.

Project #	Wafer Technology	AEC Grade	Service Model	CAR Makers (or Tier-1)	Status
Project A	65nm low power	Grade 1	RTL-in to F/G	Germany, Japan	Volume production
Project B	90nm eDRAM	Grade 2	GDS-in to F/G	Germany, Korea	Pre-qual
Project C	180nm BCD	Grade 1	GDS-in to wafer	Japan	Under qualification
Project D	28nm HPC	Grade 1	RTL-in to F/G	Germany, US	MPW Prototyping
Project E	250nm BCD	Grade 1	GDS-in to F/G	Korea	MPW Prototyping

# TSMC's Automotive Program Update

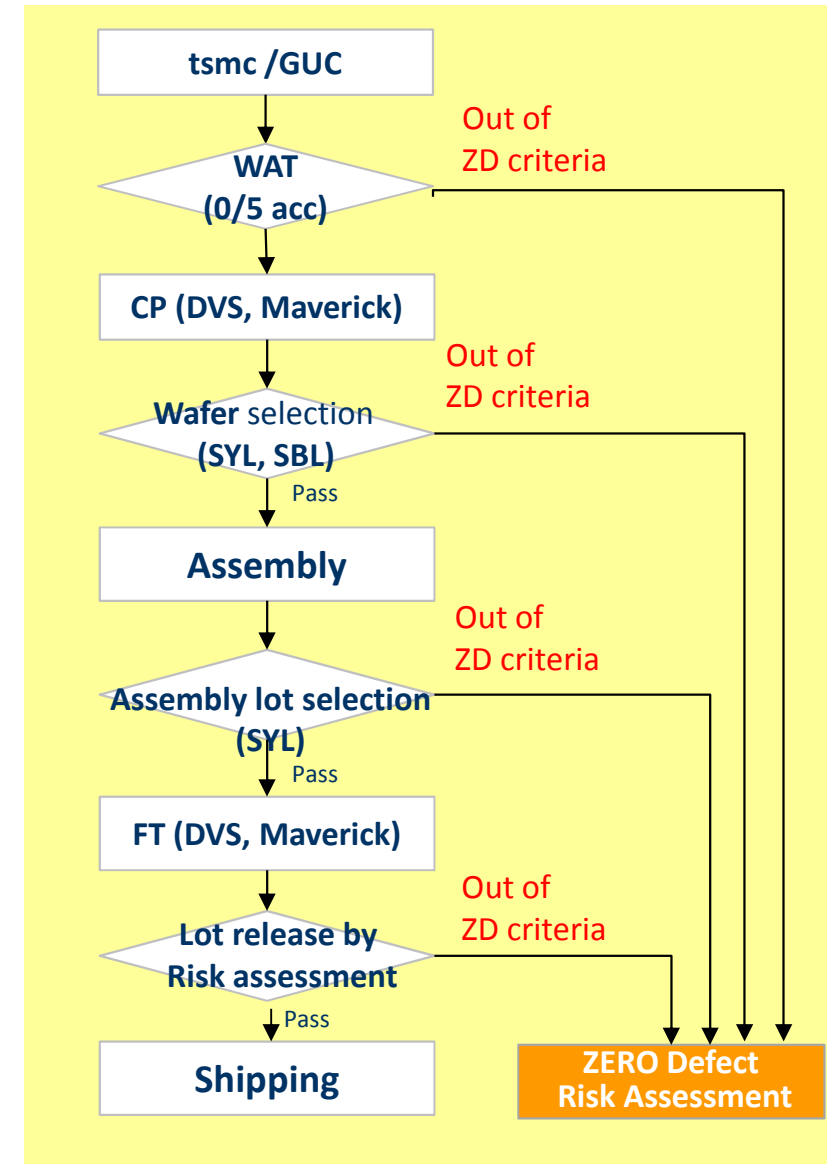
- **State of the art quality system in place**
  - ISO/TS16949, ISO14001 certified for all Fabs
  - The ultimate goal of our quality policy - Zero defect - in everything we do.
- **Focused Automotive Program established in 2008.**
  - Automotive process Qual Spec per AEC-Q100.
  - Automotive service package to eliminate outlier wafers.
  - Safe launch program to early detect failures and take corrective actions.
  - Enhancing the program through TSMC initiative and supply chain's inputs.
- **Technologies range from 0.8μm to 28nm; include logic, mixed signal, HV, CIS, Embedded Flash**
- **Started shipment to automotive industry from 1997. Shipped more than 2.1 million automotive wafers with good ppm level performance**
  - More than 800K 0.25μm EmbFlash wafers, ppm level <1 in 2013
  - More than 500K 0.18μm EmbFlash wafers, ppm level <1 in 2013
  - More than 50K 90nm Logic 12" wafers, ppm level <1 in 2013
  - More than 50K 65nm Logic 12" wafers



# Good Performance to Deliver Automotive Chips

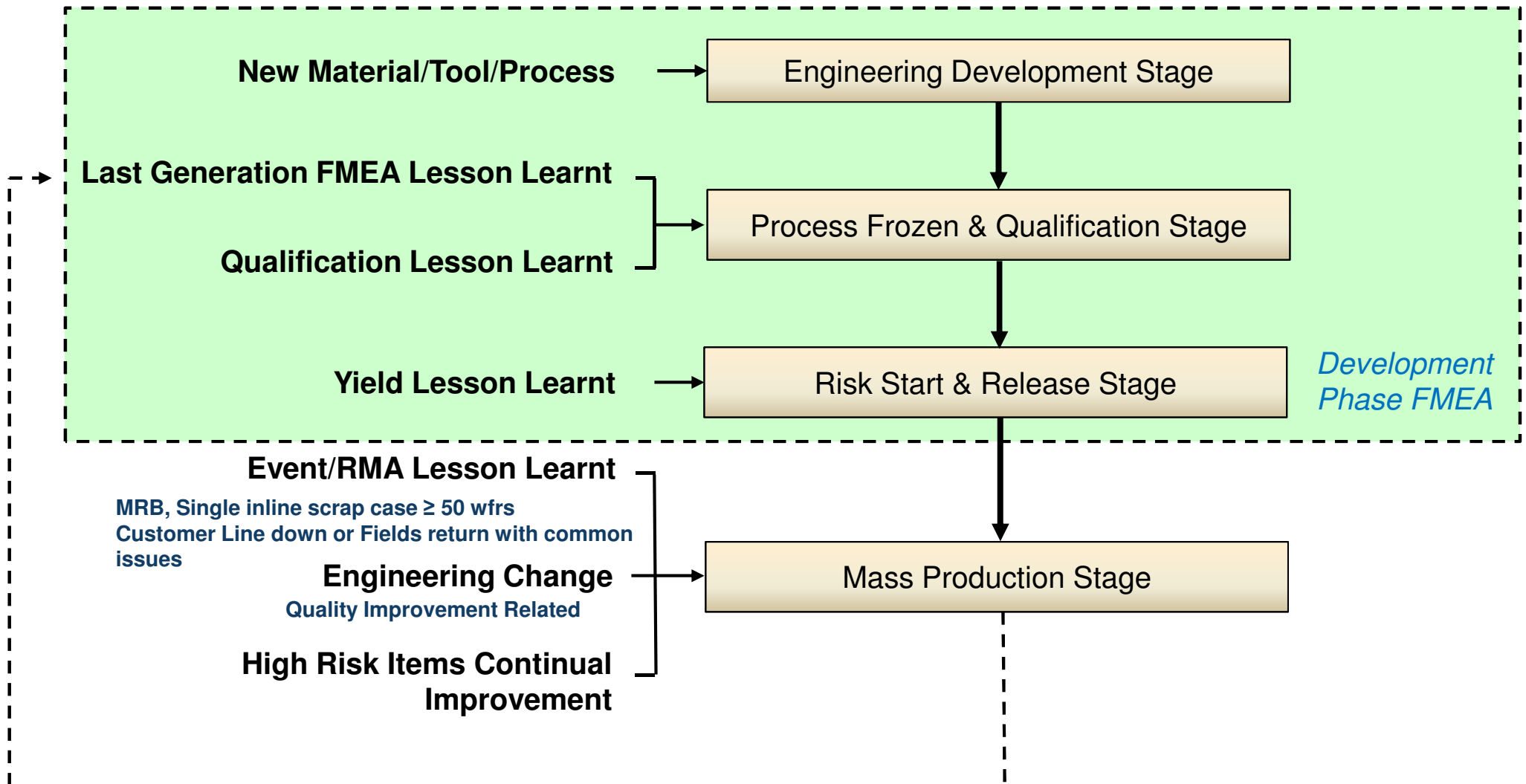
- **GPS controller ASIC, Grade 1, non-safety**
  - 65nm technology, 16x16 BGA
  - Apply **ZERO Defect program**
- ✓ **Qualified AEC Q100**
- ✓ **More than 1M units production shipment since 2010**
- ✓ **No RMA up to now**

 **ppm level < 1**



# FMEA Practice in Foundry

- Foundry FMEA Practice



# ZERO Defect Program

Phase	ZERO Defect rules
F/E, B/E Design	Tighten EM rules
	Special Design rules
	T/O guidelines
	DFT rules for ZERO Defect
	Advanced ESD/LU rules
	eFuse for traceability
Production	WAT tighten control rules
	Tighten SPC/Cpk rules
	SYL, SBL
	Part Average Testing
	Dynamic Voltage Stress Test
	Temp. Stress Test
	Maverick rules
	Geographic Defect Detection
	Quick RMA/FA
	BCP guideline
	Reliability monitor (ORM)

- **GUC will adopt design, wafer production (WAT, Cp/Cpk, Maverick), RMA and BCP.**
- **Cooperate with customer to adopt**
  - Maverick (CP, FT)
  - DVS
  - SYL and SBL
  - Geographic defect detection
  - On-going Reliability Monitor